

## Method For Grinding Semiconductor Wafers

### Abstract

- 5 The invention relates to a method for grinding a semiconductor wafer, in which the semiconductor wafer is machined for material removal by means of a grinding tool containing grinding teeth having a height  $h$ , with a cooling medium being fed into a contact region between the semiconductor wafer and the grinding tool, and, at any time during the grinding, a rinsing liquid is applied to a region on one side of the
- 10 semiconductor wafer by means of a nozzle, characterised in that the distance between the region and the centre of the semiconductor wafer is not less than 2 mm and not greater than 10 mm.

Fig. 1